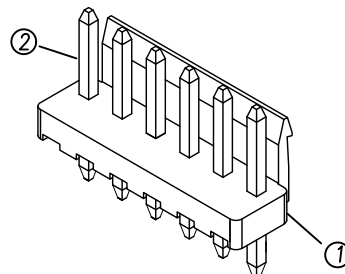
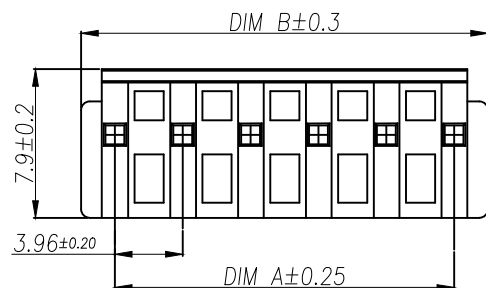


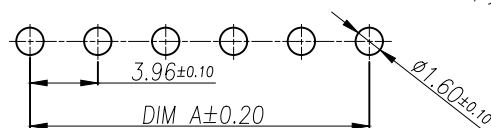
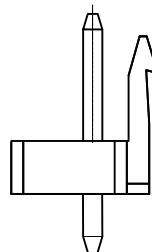
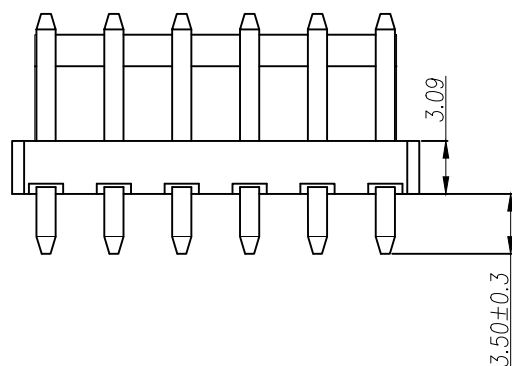
PRELIMINARY
DESIGN IS SUBJECT
TO CHANGE WITHOUT
PRIOR NOTICE



技术要求:

- 1、塑件材料:PA66 (UL-94V-0)
- 2、接触件:黄铜镀锡
- 3、接触电阻: $\leq 20m\Omega$
- 4、绝缘电阻: $\geq 1000M\Omega$
- 5、额定电压:250V AC DC
- 6、额定电流:3.0A AC DC
- 7、耐压:能承受1000V AC/Min ute
- 8、工作温度: $-25^{\circ}\sim +85^{\circ}$
- 9、可焊性试验:浸锡面积 $\geq 95\%$ 温度 $235\pm 5^{\circ}$,时间 2.5 ± 0.5 秒
- 10、铅和镉等六大有害物质含量要符合环保要求

Part No	PIN	A	B
XY-B2P-VH	2	3.96	7.92
XY-B3P-VH	3	7.92	11.88
XY-B4P-VH	4	11.88	15.84
XY-B5P-VH	5	15.84	19.80
XY-B6P-VH	6	19.80	23.76
XY-B7P-VH	7	23.76	27.72
XY-B8P-VH	8	27.72	31.68
XY-B9P-VH	9	31.68	35.64
XY-B10P-VH	10	35.64	39.60
XY-B11P-VH	11	39.60	43.56
XY-B12P-VH	12	43.56	47.52
XY-B13P-VH	13	47.52	51.48
...	...	...	...
XY-B20P-VH	20	(20-1)*3.96	20*3.96



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

2	Contact	Brass	n*1	电镀(锡): 整个表面镀底镍30u"MIN,再 镀锡80u".MIN.
1	Wafer	PA66(UL94V-0)	1	白色
序号	名称	材料	数量	附注
DIMENSION IN mm		厦门市辛译精密电子有限公司 Xiamen XinYi Xyconn Electronics Co.,Ltd		
TOLERANCE UNLESS OTHERWISE SPECIFIED				
.X $\pm$ 0.35	X.* $\pm$ 5°	APR. Alex	TITLE: WAFER 3.96mm H3.0mm 180° DIP	
.XX $\pm$ 0.25	.X.* $\pm$ 3°	CHK. Jack	DWG NO. XY-BNP-VH	
.XXX $\pm$ 0.15	.XX.* $\pm$ 1°	DRA. Can	PROJ.  CUSTOMER DRAWING	
SIZE A4	SCALE 1:1	SHEET 1/1	REV. A	